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**RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE - EXAMINING GROUP 2800**

PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

May 31, 2006
Date

Carolyn L. Ross
Carolyn L. Ross

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	: 10/801,386	Confirmation No.	: 3160
Applicant	: Tongbi Jiang		
Filed	: March 15, 2004	Attorney Docket No.:	500180.03
Art Unit	: 2814	Customer No.	: 27,076
Examiner	: Wai Sing Louie		
Title	: PRESSURE AND HEAT CURED SEMICONDUCTOR DIE PACKAGES HAVING REDUCED VOIDS IN A DIE ATTACH BONDLINE		

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Sir:

Applicant acknowledges receipt of the Office Action dated March 31, 2006.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.